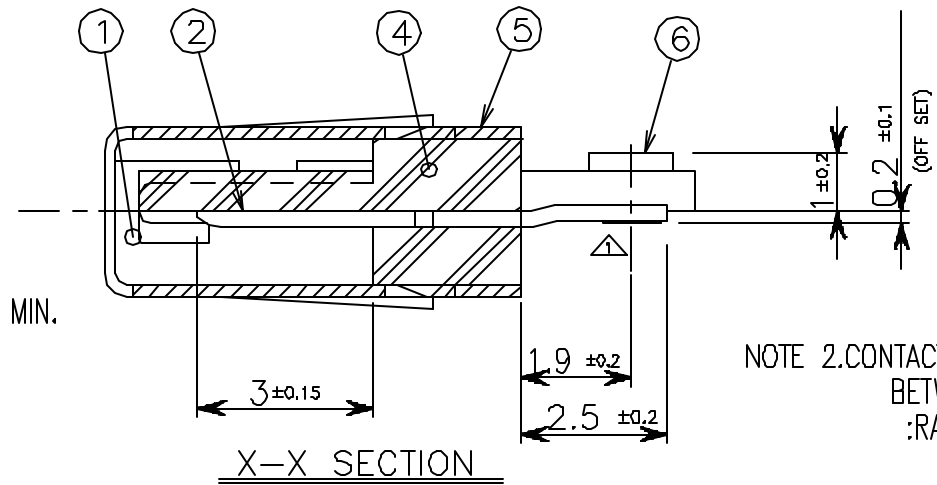
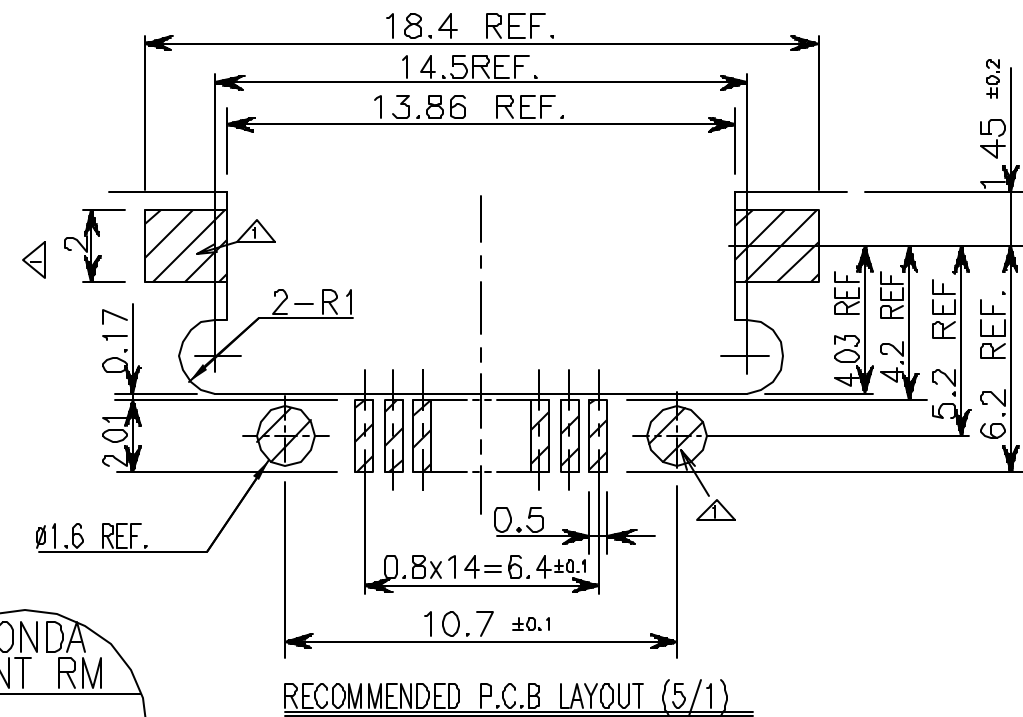
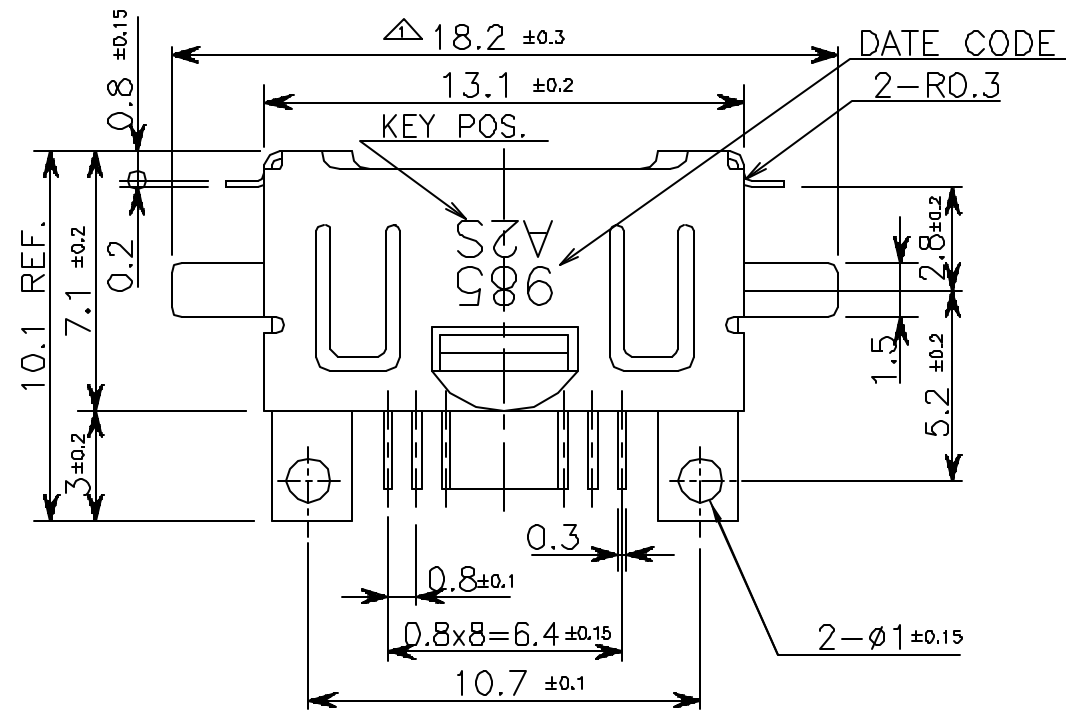
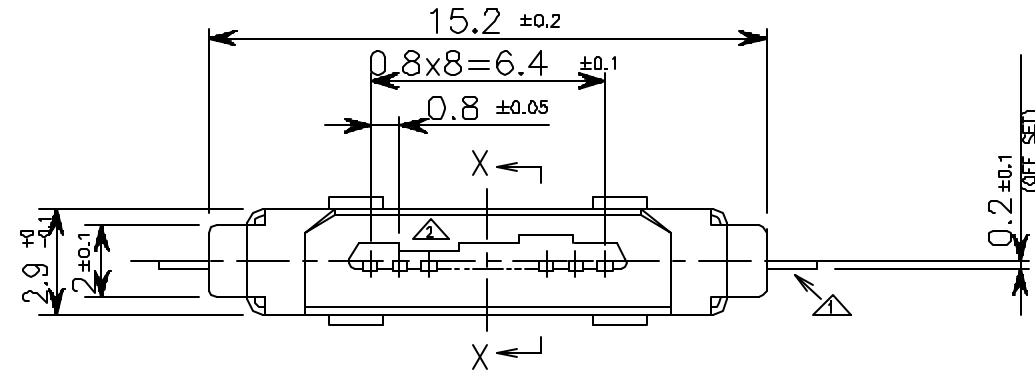


NOTE 1. CONTACT PLATING
 CONTACT AREA: GOLD 0.1μm MIN.
 OVER Pd/Ni(9:1)1μm MIN.
 TERMINAL AREA: TIN/LEAD.
 ALL OVER: Ni 1.27μm MIN.



NOTE 2. CONTACT CO-PLANARITY
 BETWEEN ALL TERMINALS
 : RANGE 0.15 MAX.



HONDA
 PRINT RM
 OCT.28.1998
 ISSUED

STANDARD POLARIZING KEY POS.

△△ PART No.	KEY POS.	MARKING	△ MATING CONNECTOR
RMC-E9MYSN-OM02-MA2	2	A2	RMC-EB9F()-BSLA()N-MA1
RMC-E9MYSN-OM02-MA1	1	A1	RMC-EB9F()-BSLA()N-MA2
RMC-E9MYSN-OM02-MA	NOTHING	A	RMC-EB9F()-BSLA()N-MA()

LTR.	DATE	BY	REV.	DESCRIPT	NO.	PART NAME	MATERIAL	QTY	FINISH	NOTE
					6	HOLD DOWN	COPPER ALLOY	2	△ NICKEL PLATING	
					5	SHELL	STAINLESS STEEL	1	NICKEL PLATING	
					4	INSULATOR	PPS(GF)	1		UL94V-0 BLACK
					3	POLARIZING KEY	PPS(GF)	1		UL94V-0 NATURAL
					2	MALE CONTACT	COPPER ALLOY	9	SEE NOTE1	
					1	LOCK PLATE	STAINLESS STEEL	2		

DATE	SCALE	UNIT	3RD . A . P	HONDA TSUSHIN KOGYO., LTD.		
APR.8 (1998)	5/1	mm(INCH)		DR	DE	CHK
				CHK	APR	NAME
						PART NO.

0.8mm PITCH SHIELDED I/O MALE
 9 POS. CONNECTOR FOR CARD
 OFF SET TAIL 0.2mm(NO SEQUENCE TYPE)
 △△ RMC-E9MYSN-OM02-MA() REV. 3C